

Small Signal Switching Chip Diode, Dual

Feature

Silicon Epitaxial Planar Diode.

Fast switching dual chip diode with anode to cathode.

This diode is also available in other configurations including single with type designation CDMMBD4148, a dual common anode with type designation CDBAV70, and a dual common cathode with type designation CDBAW56

Lead (Pd) - free component.

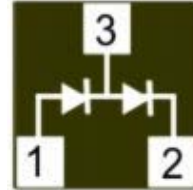
Cathode Band Color: white



Case: SOT23 Plastic Case

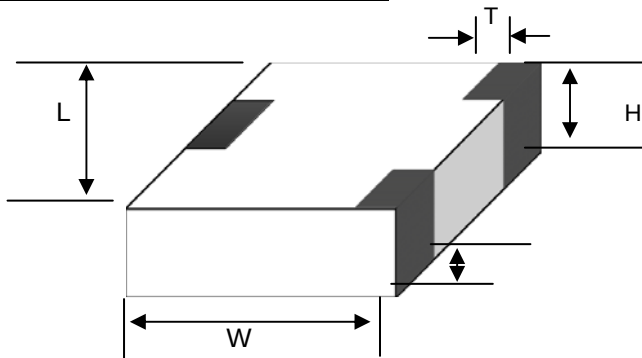
Weight: approx. 21mg

Value: CDBAV99



Mounting Pad Layout

DIMENSION:			
(mm)	CDBAV56	CDBAV70	CDBAV99
L	3.1 ± 0.2	3.1 ± 0.2	3.1 ± 0.2
W	2.6 ± 0.2	2.6 ± 0.2	2.6 ± 0.2
H	0.95 ± 0.2	0.95 ± 0.2	0.95 ± 0.2
T	0.75 ± 0.2	0.75 ± 0.2	0.75 ± 0.2
C	0.8 ± 0.1	0.8 ± 0.1	0.8 ± 0.1



Maximum Ratings & Electrical Characteristics $T_{amb} = 25^{\circ}\text{C}$, unless otherwise noted

Parameter	Symbol	Value	Unit
Device marking code		CDBAV99	
Non repetitive peak reverse voltage	V_{RM}	100	V
Reprtitive pead reverse voltage	$V_R = V_{RRM}$	70	V
Forward continuous current	I_F	200	mA
Non repetitive peak forward current	I_{FSM}	2.0	A
$t_p = 1 \mu\text{s}$		1.0	
$t_p = 1 \text{ ms}$		0.5	
Average forward current	I_{FSM}	150 ¹⁾	mA
Power dissipation	P_{TOT}	300 ¹⁾	mW
Forward voltage	V_F	IF = 1mA 855	mV
		IF = 10mA 1000	
		IF = 50mA 1250	
		IF = 150mA	
Leakage current	I_R	VR = 70V 2.5	μA
		VR = 70V, $T_J = 150^{\circ}\text{C}$ 50	
		VR = 25V, $T_J = 150^{\circ}\text{C}$ 30	
Thermal resistance junction to ambient air	R_{thJA}	430 ¹⁾	K/W
Junction temperature	T_J	150	$^{\circ}\text{C}$
Storage temperature range	T_{stg}	- 55 to + 150	$^{\circ}\text{C}$
Diode capacitance ($V_F = V_R = 0$, $f = 1\text{MHz}$)	C_{tot}	2	pF
Reverse Recovery time ($I_F = 10\text{mA}$ to $I_R = 1\text{mA}$, $V_R = 6\text{V}$, $R_L = 100\Omega$)	T_{rr}	6	ns

¹⁾ Valid provided that eletrodrs are kept at ambient temperature.

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Typical Characteristics

(Tamb=25°C, unless otherwise specified)

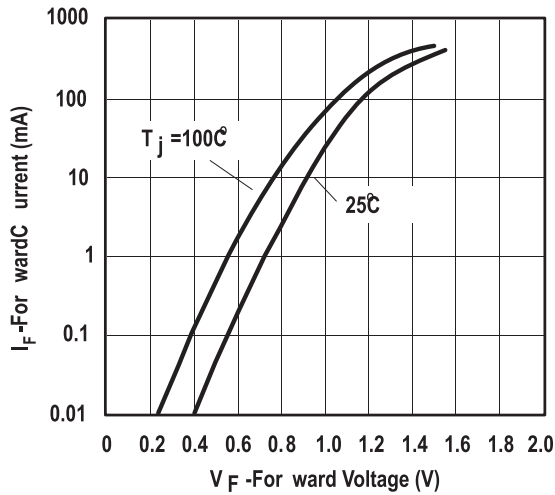


Figure1. Forward Current vs. Forward Voltage

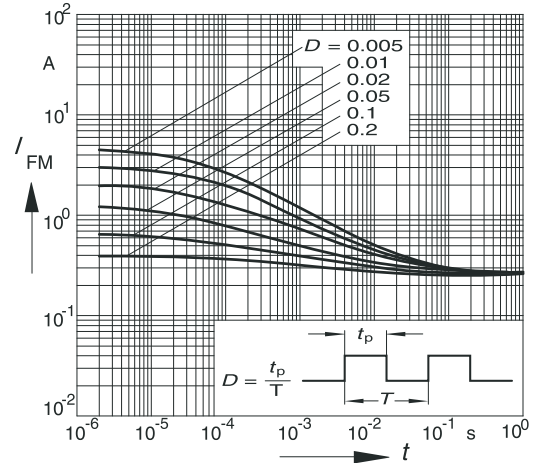
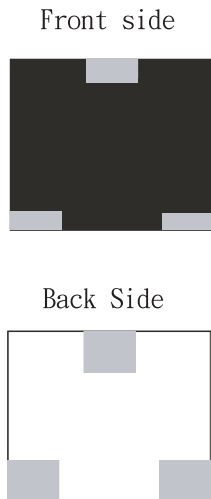
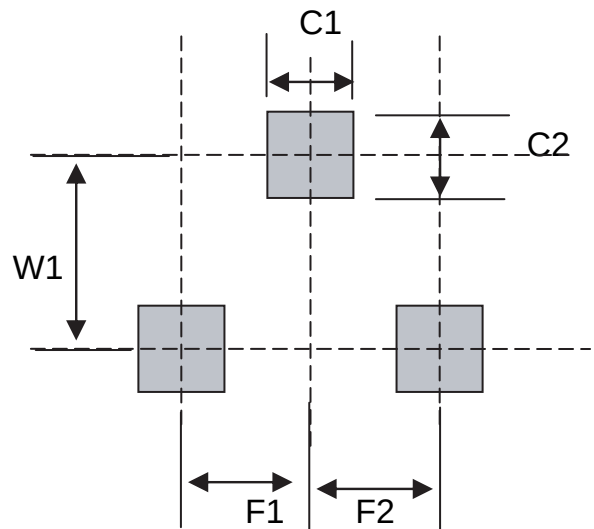


Figure2. Peak forward current $I_{FM} = f(t_p)$

Device outlook



Mounting Pad Layout



Mounting Pad Layout			
Typ.(mm)	CDBAW56	CDBAV70	CDBAV99
W1	2.0	2.0	2.0
C1	0.9	0.9	0.9
C2	0.9	0.9	0.9
F1	1.14	1.14	1.14
F2	1.14	1.14	1.14

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Suggested thermal profiles for soldering processes

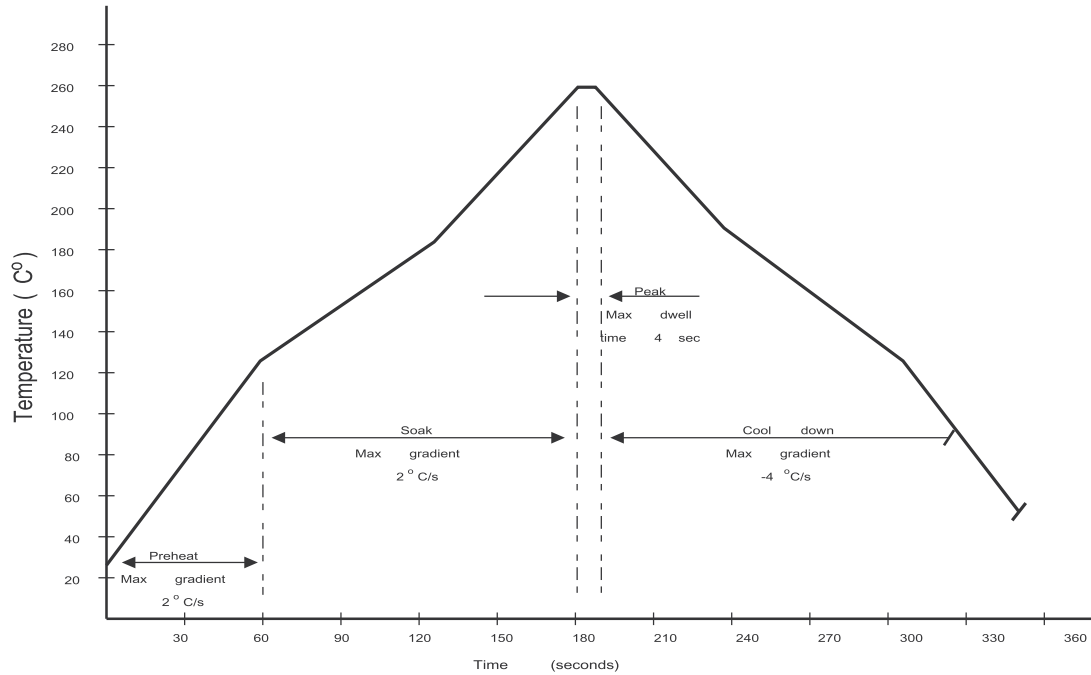


Fig.1 Typical Wave Soldering Thermal Profile

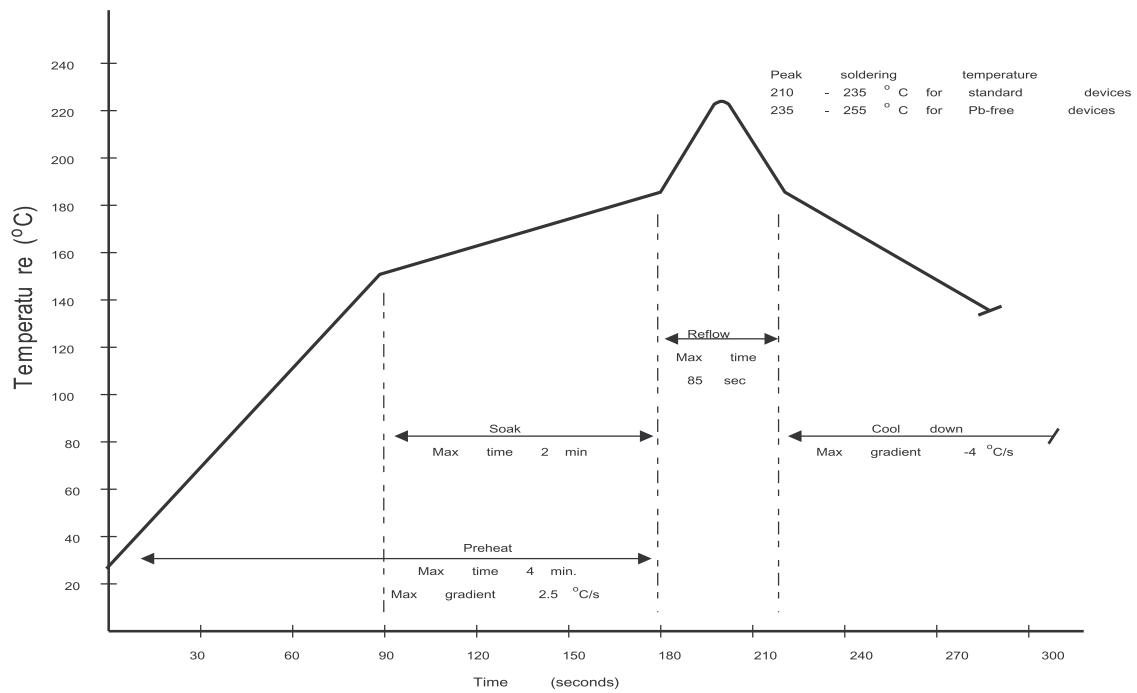


Fig.2 Typical IR Reflow Soldering Thermal Profile



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